EAST SEARCH for Paper no. 3

L	Hits	Search Text	/ //(	·
L Number			DB	Time stamp
1	8	("4149310" "5249101" "5903046")[pn]	USPAT;	2001/06/11
			US-PGPUB;	20:31
			EPO; JPO;	
			DERWENT;	
_	0	low with modulus with high with enlongat\$	IBM TDB USPAT;	2001/06/07
	•	with dielectric	US-PGPUB	18:55
	0		USPAT;	2001/06/07
		same dielectric	US-PGPUB	18:56
-	0	modulus with enlongat\$ with dielectric	USPAT;	2001/06/07
		J	US-PGPUB	18:56
_	21	modulus with strain with dielectric	USPAT;	2001/06/07
			US-PGPUB	18:57
-	41	modulus with stress with dielectric	USPAT;	2001/06/07
		1	US-PGPUB	19:19
-	83		USPAT;	2001/06/07
_	1	with dielectric and (257/\$ 438/\$)	US-PGPUB	20:24
-	1	5841193.pn.	USPAT; US-PGPUB	2001/06/07
_	9	("4630096"   "4827328"   "4860166"	USPAT	20:30
		"4907062"   "5049980"   "5091769"	JOFAI	20:24
		"5111278"   "5250843"   "5315486").PN.		20.27
_	2	5841193.URPN.	USPAT	2001/06/07
				20:24
_	30	FR4 adj circuit adj board	USPAT;	2001/06/07
			US-PGPUB	20:37
-	554	(printed adj circuit adj board PCB) same	USPAT;	2001/06/07
		solder adj balls and (257/\$.ccls.	US-PGPUB	20:39
		438/\$.ccls.)		
-	50	FR4 adj printed adj circuit adj board	USPAT;	2001/06/07
	1 200		US-PGPUB	21:05
-	202	eichelberger.in.	USPAT;	2001/06/07
_	40	eichelberger.in. and (257/\$ 438/\$)	US-PGPUB	21:06 2001/06/07
-	40	elonethergel.in. and (25//\$ 430/\$)	USPAT; US-PGPUB	21:09
_	0	(eichelberger.in. and (257/\$ 438/\$)) and	USPAT;	2001/06/07
		enlongat\$	US-PGPUB	21:09
_	0	eichelberger.in. and enlongat\$	USPAT;	2001/06/07
			US-PGPUB	21:11
-	14	eichelberger.in. and thermal adj	USPAT;	2001/06/07
		expansion	US-PGPUB	21:49
_	0	(eichelberger.in. and thermal adj	USPAT;	2001/06/07
	_	expansion) and modulus	US-PGPUB	21:12
-	0	(eichelberger.in. and thermal adj	USPAT;	2001/06/07
	200	expansion) and modulus	US-PGPUB	21:12
_	288	expansion same modulus same dielectric	USPAT;	2001/06/07
	47	(expansion same modulus same dielectric)	US-PGPUB USPAT;	21:49 2001/06/07
	",	and (257/\$ 438/\$)	US-PGPUB	22:27
_	17	low adj modulus same (CTE expansion	USPAT;	2001/06/07
	-	enlongation fracute) same dielectric	US-PGPUB	22:29
_	19	low adj modulus same (CTE expansion	USPAT;	2001/06/07
		enlongation fracture) same dielectric	US-PGPUB	22:33
_	2	(low adj modulus same (CTE expansion	USPAT;	2001/06/07
		enlongation fracture) same dielectric)	US-PGPUB	22:35
		not (low adj modulus same (CTE expansion		
		enlongation fracute) same dielectric)		
_	0	low adj modulus same high adj enlongation	USPAT;	2001/06/07
		]	US-PGPUB	22:35
-	0	low adj modulus same enlongation	USPAT;	2001/06/07
_	0	low add modulus and enlongstion	US-PGPUB	22:35
_	"	low adj modulus and enlongation	EPO; JPO;	2001/06/07 22:36
			DERWENT; IBM TDB	22:30
_	555	low adj modulus and fracture	USPAT;	2001/06/07
	333	20. auj modulus diid lluosalo	US-PGPUB	22:36
_	18	low adj modulus and fracture	EPO; JPO;	2001/06/07
			DERWENT;	22:36
	]		IBM TDB	
	-L			

-	64	low adj modulus same fracture	USPAT;	2001/06/07
-	611	low adj modulus same elongation	US-PGPUB USPAT;	22:46 2001/06/07
-	5	1	US-PGPUB USPAT;	22:47 2001/06/07
_	5	dielectric low adj modulus and elongation and	US-PGPUB EPO; JPO;	22:48
		dielectric	DERWENT; IBM TDB	22:52
-	51	modulus and elongation and dielectric	EPO; JPO;	2001/06/07
			DERWENT; IBM TDB	22:52
-	1427	modulus and elongation and dielectric	USPAT; US-PGPUB	2001/06/07 22:52
-	247	modulus same elongation same dielectric	USPAT; US-PGPUB	2001/06/07
-	6	( The same of the	USPAT;	2001/06/07
_	699	and (257/\$ 438/\$) acrylated adj urethane	US-PGPUB USPAT;	23:20 2001/06/07
_	8	(acrylated adj urethane) and (257/\$	US-PGPUB USPAT;	23:20 2001/06/07
		438/\$)	US-PGPUB	23:39
_	0		USPAT	2001/06/08 00:24
-	79	long with displac\$ and (257/\$ 438/\$)	USPAT	2001/06/08
-	246	length with displac\$ and (257/\$ 438/\$)	USPAT	2001/06/08
-	18	length with displac\$ with (wir\$ conductor interconnect) and (257/\$ 438/\$)	USPAT	2001/06/08
-	23		USPAT; US-PGPUB;	2001/06/08
		1	EPO; JPO;	13.70
			DERWENT; IBM TDB	
-	1	5903046.pn. and modulus	USPAT; US-PGPUB;	2001/06/08 16:33
			EPO; JPO;	10.00
			DERWENT; IBM TDB	
-	1	5249101.pn. and (elongation fracture)	USPAT; US-PGPUB;	2001/06/08
			EPO; JPO;	10.52
			DERWENT; IBM TDB	
-	0	5249101.pn. and dielectric	USPAT;	2001/06/08
			US-PGPUB; EPO; JPO;	16:52
			DERWENT; IBM TDB	
-	0	5249101.pn. and insulator	USPAT;	2001/06/08
			US-PGPUB; EPO; JPO;	16:52
			DERWENT;	
-	4	acrylated adj urethane with dielectric	IBM TDB USPAT;	2001/06/08
			US-PGPUB; EPO; JPO;	16:55
			DERWENT;	
-	0	(acrylated adj urethane with dielectric)	IBM TDB USPAT;	2001/06/08
		and elongation	US-PGPUB; EPO; JPO;	17:31
			DERWENT;	
_	602	modulus with copper	IBM TDB USPAT;	2001/06/08
		· FF	US-PGPUB;	17:32
			EPO; JPO; DERWENT;	
L	<u>                                      </u>		IBM TDB	

_				
-	0	modulus with copper adj interconnect	USPAT; US-PGPUB; EPO; JPO;	2001/06/08 17:32
			DERWENT; IBM TDB	
_	12	modulus with copper adj wire	USPAT; US-PGPUB;	2001/06/08 17:36
			EPO; JPO; DERWENT; IBM TDB	
-	49	(modulus with copper) and (257/\$ 438/\$)	USPAT; US-PGPUB;	2001/06/08
			EPO; JPO; DERWENT;	
-	13	(("Young's" "young") with modulus with copper) and (257/\$ 438/\$)	IBM TDB USPAT; US-PGPUB;	2001/06/08
			EPO; JPO; DERWENT;	
_	13	(("Young's" "young's") with modulus with	IBM TDB USPAT;	2001/06/08
		copper) and (257/\$ 438/\$)	US-PGPUB; EPO; JPO;	20:30
			DERWENT; IBM TDB	
_	13	(("Young" "young") with modulus with copper) and (257/\$ 438/\$)	USPAT; US-PGPUB;	2001/06/08 20:31
-			EPO; JPO; DERWENT; IBM TDB	
_	23	length with displac\$ with (wir\$ conductor interconnect) and (257/\$ 438/\$)	USPAT; US-PGPUB;	2001/06/08 21:15
			EPO; JPO; DERWENT;	
_	12	expansion with (wir\$ conductor interconnect) with displac\$ and (257/\$	IBM TDB USPAT; US-PGPUB;	2001/06/08
		438/\$)	EPO; JPO; DERWENT;	21.33
_	17	expansion with (wir\$ conductor	IBM TDB USPAT;	2001/06/08
		interconnect) same displac\$ and (257/\$ 438/\$)	US-PGPUB; EPO; JPO;	21:43
			DERWENT; IBM TDB	
_	5	(expansion with (wir\$ conductor interconnect) same displac\$ and (257/\$ 438/\$)) not (expansion with (wir\$	USPAT; US-PGPUB;	2001/06/08 21:41
		conductor interconnect) with displac\$ and (257/\$ 438/\$))	EPO; JPO; DERWENT; IBM TDB	
_	15	expansion same (wir\$ conductor interconnect) same length same displac\$	USPAT; US-PGPUB;	2001/06/08
		and (257/\$ 438/\$)	EPO; JPO; DERWENT;	
_	11	(expansion same (wir\$ conductor	IBM TDB USPAT;	2001/06/08
		interconnect) same length same displac\$ and (257/\$ 438/\$)) not ((expansion with	US-PGPUB; EPO; JPO;	21:51
		<pre>(wir\$ conductor interconnect) same displac\$ and (257/\$ 438/\$)) not (expansion with (wir\$ conductor</pre>	DERWENT; IBM TDB	
		<pre>interconnect) with displac\$ and (257/\$ 438/\$))) not (expansion with (wir\$</pre>		0
		<pre>conductor interconnect) same displac\$ and (257/\$ 438/\$))</pre>		
-	100	thermal adj expansion with displac\$ and (257/\$ 438/\$)	USPAT; US-PGPUB;	2001/06/09 00:56
			EPO; JPO; DERWENT; IBM TDB	

-	3	5841193.pn.	USPAT;	2001/06/11
			US-PGPUB;	20:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	